30 April 2003

09/762,582

L Number	Hits	Search Text	DB	Time stamp
-	0	762582.apn.	USPAT;	2003/04/29
		·	US-PGPUB;	11:23
			EPO; JPO;	-
	9	···	DERWENT	
-	9	(("5116430") or ("3716462") or ("3930963")).PN.	USPAT;	2003/04/29
			US-PGPUB;	13:53
			EPO; JPO;	
		• •	DERWENT	
-	. 1	jp-51149131-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	12:13
, '			EPO; JPO;	•
			DERWENT	
-	2	4163705.pn.	USPAT;	2003/04/29
			US-PGPUB;	12:13
			EPO; JPO;	
*			DERWENT	
<u>.</u> ,	7	(("5849171") or ("4430173") or ("5433840")).PN.	USPAT;	2003/04/30
	,	((	US-PGPUB;	09:43
			EPO; JPO;	
			DERWENT	
•	2657	204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
-	2037	LO. 17 170, E1E, EO E, E TE, E 1 0, E 1 0.1.0013.	US-PGPUB;	13:55
			EPO; JPO;	15.55
			DERWENT	
	. 773	204/224r.ccls. /	USPAT;	2003/04/29
<del>-</del>	773	204/224r.ccis.	US-PGPUB;	13:55
			EPO; JPO;	13.55
			DERWENT	
	2270	204/400 242 222 242 272 275 1 - 12 204/22412		2003/04/29
-	3270	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	1
		•	US-PGPUB;	13:55
			EPO; JPO;	
			DERWENT	0000 (04 (00
<u>-</u>	35	(204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/29
:		204/224r.ccls.) and electroless and (electrolytic or	US-PGPUB;	14:04
		electroplating) and robot	EPO; JPO;	
			DERWENT	
-	58753	204/\$.ccls.	USPAT;	2003/04/29
			US-PGPUB;	14:04
			EPO; JPO;	
			DERWENT	
-	55	204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot	US-PGPUB;	14:04
			EPO; JPO;	
		·	DERWENT	
<b>-</b>	20	(204/\$.ccls. and electroless and (electrolytic or	USPAT;	2003/04/29
		electroplating) and robot) not	US-PGPUB;	14:14
		((204/198,212,232,242,273,275.1.ccls.	EPO; JPO;	
		204/224r.ccls.) and electroless and (electrolytic or	DERWENT	
		electroplating) and robot)		
_	2	6080291.pn.	USPAT;	2003/04/29
		0000E71.pm	US-PGPUB;	14:07
			EPO; JPO;	
	.		DERWENT	

-	813	204/\$.ccls. and (robot or robotic)	USPAT;	2003/04/29
			US-PGPUB;	14:14
	1	·	EPO; JPO;	
			DERWENT	
_	78	(204/\$.ccls. and (robot or robotic)) and electroless	USPAT;	2003/04/29
	, ,	(20 ) \$\psi.cols. and (1000) of 1000 (10), and olsowers	US-PGPUB;	14:15
			EPO; JPO;	
			DERWENT	
	81	204/\$.ccls. and electroless and (robot or robotic or	USPAT:	2003/04/29
-	01	(transfer adjunit) or (transfer adj device) or	US-PGPUB;	14:16
			EPO; JPO;	14.10
		(transfer adj arm))	DERWENT	
	. 24	(204/thick and all about as and (ash at an ash atic as	ł	2002/04/20
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:17
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	•
		and (electrolytic or electroplating) and robot) not	DERWENT	
		((204/\$.ccls. and electroless and (electrolytic or	.]	
		electroplating) and robot) not		
		((204/198,212,232,242,273,275.1.ccls.		
	1	204/224r.ccls.) and electroless and (electrolytic or		
-		electroplating) and robot))		
-	26	(204/\$.ccls. and electroless and (robot or robotic or	USPAT;	2003/04/29
		(transfer adj unit) or (transfer adj device) or	US-PGPUB;	14:33
		(transfer adj arm))) not (204/\$.ccls. and electroless	EPO; JPO;	
1		and (electrolytic or electroplating) and robot) not	DERWENT	
		((204/198,212,232,242,273,275.1.ccls.		
		204/224r.ccls.) and electroless and (electrolytic or		•
		electroplating) and robot)		
· <b>-</b>	2	6197181.pn.	USPAT;	2003/04/29
			US-PGPUB;	14:21
			EPO; JPO;	
	·		DERWENT	
-	2	jp-56158424-\$.did.	USPAT;	2003/04/29
		· ·	US-PGPUB;	14:34
			EPO; JPO;	
			DERWENT	
_	1	1982-04830E.NRAN.	DERWENT	2003/04/29
				14:33
-	. 2	jp-05311496-\$.did.	USPAT;	2003/04/29
	_	UF TOTAL TOTAL	US-PGPUB;	14:35
	ĺ		EPO; JPO;	
			DERWENT	
<u> </u>	2	jp-07193214-\$.did.	USPAT;	2003/04/29
		19 0/120E1   #.did.	US-PGPUB:	14:37
			EPO: JPO:	1
			DERWENT	
	1	1995-217803.NRAN.	DERWENT	2003/04/29
_	1	1273-617 003.1NM.	DERVEINI	14:37
	2	in 02000341 \$ did	USPAT;	2003/04/29
-	2	jp-02000341-\$.did.	l .	
· ·			US-PGPUB;	14:39
			EPO; JPO;	
		4000 04704E ND 4N	DERWENT	2002/04/20
-	1	1990-047945.NRAN.	DERWENT	2003/04/29
				14:39

	-	I	I <b></b>	
-	. 2	jp-56161221-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:42
			EPO; JPO;	
			DERWENT	
-	1	jp-51149131-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:43
		·	EPO; JPO;	
			DERWENT	
	1	1976-75692X.NRAN.	DERWENT	2003/04/29
				14:42
	2	jp-03146698-\$.did.	USPAT;	2003/04/29
· · · .	_	10 1000 Aim.	US-PGPUB;	14:44
			EPO; JPO;	A 11 1 1
			DERWENT	
	2	in 05009500 ¢ did	1	2002/04/20
-	2	jp-05098500-\$.did.	USPAT;	2003/04/29
		•	US-PGPUB;	14:45
			EPO; JPO;	
•			DERWENT	
•	2	jp-62235499-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:46
			EPO; JPO;	
			DERWENT	
-	2	jp-63026400-\$.did.	USPAŤ;	2003/04/29
			US-PGPUB;	14:50
			EPO; JPO;	
			DERWENT	
-	1	1997wo-??22733.ap,prai.	USPAT;	2003/04/29
	-		US-PGPUB;	14:51
• .		·	EPO; JPO;	
			DERWENT	
_	0	wo-22733-\$.did.	USPAT;	2003/04/29
	. 0	wo-ke/30=\u00e4.uid.	US-PGPUB;	14:52
			EPO; JPO;	17.36
•				
		00033733 ¢ 4:4	DERWENT	2002/04/20
-	. 0	wo-00022733-\$.did.	USPAT;	2003/04/29
			US-PGPUB;	14:52
			EPO; JPO;	
,			DERWENT	
-	0	wo-97022733-\$.did.	USPAT;	2003/04/29
	•	·	US-PGPUB;	14:52
		'	EPO; JPO;	
			DERWENT	•
-	58753	204/\$.ccls.	USPAT;	2003/04/29
		·	US-PGPUB;	15:10
		<u>'</u>	EPO; JPO;	
			DERWENT	
-	708	204/\$.ccls. and (electroless and (electrolytic or	USPAT;	2003/04/29
	'	electroplating or electroplate))	US-PGPUB;	15:11
		Community of Community	EPO; JPO;	
			DERWENT	
_	82	(204/\$.ccls. and (electroless and (electrolytic or	USPAT;	2003/04/29
-	02	· · · · · · · · · · · · · · · · · · ·		
		electroplating or electroplate))) and (robot or robotic	US-PGPUB;	15:12
		or ((transfer or conveyance or conveyor) adj (means!	EPO; JPO;	
		or unit or device or system or arm)))	DERWENT	



-	160054	205/\$.ccls. or 427/\$.ccls.	USPAT;	2003/04/29
		•	US-PGPUB;	15:47
			EPO; JPO;	
			DERWENT	
_	14963	(205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)	US-PGPUB;	15:48
			EPO; JPO;	15.10
			DERWENT	-
_	759	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
	/ 39	wafer)) and electroless and (electroplating or	1	15:49
			US-PGPUB;	19:49
		electroplated or electroplate or electrolytic or	EPO; JPO;	
	E4	electrochemically)	DERWENT	2002 (0.4 (0.0
-	54	((205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath)) and	US-PGPUB;	15:49
		((electroplating or electroplated or electroplate or	EPO; JPO;	
_		electrolytic or electrochemically) near2 (tank or	DERWENT	
,		bath))		
	60	((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:54
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	
-		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))		
-	, 7	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:51
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	
		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))) and (robot or		
•	·	robotic or ((transfer or conveyor or conveyance) near		
-	,	(arm or unit or device or means!)))		
_	29	(((205/\$.ccls. or 427/\$.ccls.) and (semiconductor or	USPAT;	2003/04/29
		wafer)) and (electroless near2 (tank or bath or	US-PGPUB;	15:55
		chamber)) and ((electroplating or electroplated or	EPO; JPO;	10.00
		electroplate or electrolytic or electrochemically)	DERWENT	
		near2 (tank or bath or chamber))) and ((copper adj	DERWEIT	
		sulfate) or "Cuso.sub.4")		· ·
	8	(("5500315") or ("5310580") or ("5389496") or	USPAT;	2003/04/30
		(( 550515 ) of ( 5515566 ) of ( 5565450 ) of ( 5515566 ) of ( 551566 ) of ( 551666 ) of ( 5516	US-PGPUB;	08:52
		( 0109010 J).FIN.	EPO; JPO;	00.02
			l .	
	_	alastralass and ((sames adi sulfate) as lieuse and 40)	DERWENT	2002/04/20
•	0	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
		and ((chlorine or chloride) adj ions) and (sufuric adj	US-PGPUB;	08:54
		acid)	EPO; JPO;	
			DERWENT	0000 (0 : 100
-	1896	electroless and ((copper adj sulfate) or "cuso.sub.4")	USPAT;	2003/04/30
		·	US-PGPUB;	08:54
			EPO; JPO;	
			DERWENT	
-	1019	(electroless and ((copper adj sulfate) or "cuso.sub.4"))	USPAT;	2003/04/30
		and (sulfuric adj acid)	US-PGPUB;	08:54
	•		EPO; JPO;	
			DERWENT	



	<del></del>		T	<del></del>
•	220	((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or pegl or	EPO; JPO;	
		ppg!)	DERWENT.	
-	52	(((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	08:55
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	
		ppg!)) and sulfur and nitrogen	DERWENT	
•	51	((((electroless and ((copper adj sulfate) or	USPAT;	2003/04/30
		"cuso.sub.4")) and (sulfuric adj acid)) and	US-PGPUB;	09:06
		(((polyethylene or polypropylene) adj glycol) or peg! or	EPO; JPO;	
		ppg!)) and sulfur and nitrogen) and (chlorine or	DERWENT	· ·
•		chloride)		
•	0	uk-1222969-\$.did.	USPAT;	2003/04/30
			US-PGPUB;	09:07
	]		EPO; JPO;	
			DERWENT	
	1	gb-1222969-\$.did.	USPAT;	2003/04/30
	ļ.	3	US-PGPUB:	09:11
			EPO; JPO;	09.11
			DERWENT	
•	59	(204/\$.ccis. or 205/\$.ccis.) and bubble and (pressure		2003/04/30
•	59	1 ' '	USPAT;	1
		near (module or modulation or modulating or pulse or	US-PGPUB;	10:01
		pulsating or pulsed or pulsing or pulsated or varied or	EPO; JPO;	
		variable or cyclical))	DERWENT	
	8	(204/\$.ccls. or 205/\$.ccls.) and (bubble with	USPAT;	2003/04/30
		(pressure near (module or modulation or modulating or	US-PGPUB;	10:09
		pulse or pulsating or pulsed or pulsing or pulsated or	EPO; JPO;	
		varied or variable or cyclical)))	DERWENT	
	111	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same	USPAT;	2003/04/30
		(pressure near (module or modulation or modulating or	US-PGPUB;	10:20
		pulse or pulsating or pulsed or pulsing or pulsated or	EPO; JPO;	
; *		varied or variable or cyclical)))	DERWENT	
<del>.</del> .	102	(204/\$.ccls. or 205/\$.ccls.) and ((bubble or gas) same	USPAT;	2003/04/30
		(pressure near (modulate or modulation or modulating	US-PGPUB;	13:38
		or pulse or pulsating or pulsed or pulsing or pulsated	EPO; JPO;	
•		or varied or variable or cyclical)))	DERWENT	
-	21529	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
* .		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:19
		(circuit board))	EPO; JPO;	
			DERWENT	
	2051	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
,		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:19
		(circuit board))) and bubble	EPO; JPO;	
			DERWENT	
•.	241	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
•		wafer or microelectronic or (integrated adj circuit) or	US-PGPUB;	10:20
		(circuit board))) and (bubble with pressure)	EPO; JPO;	
		(2 22 book ayy) and (babbio with pi book by	DERWENT	

	69	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor or	USPAT;	2003/04/30
-	09	1 77	US-PGPUB;	10:21
		wafer or microelectronic or (integrated adj circuit) or	1	10:21
	-	(circuit board))) and ((bubble or gas) same (pressure	EPO; JPO;	
		near (modulate or modulation or modulating or pulse or	DERWENT	•.
	•	pulsating or pulsed or pulsing or pulsated or varied or variable or cyclical)))		
-	· 2	5865894.pn.	USPAT;	2003/04/30
			US-PGPUB;	13:41
			EPO; JPO;	
		·	DERWENT	
-	83136	204/\$.ccls. or 205/\$.ccls.	USPAT;	2003/04/30
			US-PGPUB;	13:41
			EPO; JPO;	
ŀ			DERWENT	
-	18	(204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
		(bubbles with (sonic or ultrasonic or megasonic))	US-PGPUB;	13:45
		(,,,,,	EPO; JPO;	
			DERWENT	•
_	2	((204/\$.ccls. or 205/\$.ccls.) and (semiconductor) and	USPAT;	2003/04/30
	_	(bubbles with (sonic or ultrasonic or megasonic))) and	US-PGPUB;	13:45
		(hermetically or sealed)	EPO; JPO;	
		(Normany or Boardy)	DERWENT	
_	10914	204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
-	,0011	205/88,98,122,123,125,148,157,183,184,187,261,291.cc	1 .	14:07
:		427/96,98,443.1.ccls.	EPO; JPO;	11.07
	•	4277 70,70,440.1.0013.	DERWENT	
	1933 .	(204/198,212,232,242,273,275.1.ccls. 204/224r.ccls.	USPAT;	2003/04/30
	1,555	205/88,98,122,123,125,148,157,183,184,187,261,291.cc	1	14:07
		427/96,98,443.1.ccls.) and semiconductor	EPO; JPO;	11.07
ļ		4277 70,70,1 10.1.ccis.) and semiconductor	DERWENT	
_	506	((204/198,212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
	300	204/224r.ccls.	US-PGPUB;	14:07
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc	Į.	14.07
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
	135	(1620461698,212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
	133	204/224r.ccls.	US-PGPUB;	14:08`
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc	· ·	17.00
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or	DERVEINI	
	61	((4(1804/1698))212,232,242,273,275.1.ccls.	USPAT;	2003/04/30
-	.01	((((((((((((((((((((((((((((((((((((((	US-PGPUB;	14:11
1		204/224r.ccis.   205/88,98,122,123,125,148,157,183,184,187,261,291.cc	1	17.11
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc 427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
	-	· · · · · · · · · · · · · · · · · · ·	UCKWENI	
	. 10	electroless) and ((copper adj (sulfate or sulphate)) or	LICDAT	2003/04/30
•	18	(((((804/b98))) 127/2 3(2)/2420,1273;275;1mod)s.	USPAT; US-PGPUB;	14:12
	•	204/224r.ccls.	1	14.16
		205/88,98,122,123,125,148,157,183,184,187,261,291.cc		
		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless) and ((copper adj (sulfate or sulphate)) or	LICDAT	2002/04/20
	2	((((&Q4/b98)))12nd 3(20)842 A7750,B3561.oochtrasnfer)	USPAT;	2003/04/30
		204/224r.ccls.	US-PGPUB;	14:12
	,	205/88,98,122,123,125,148,157,183,184,187,261,291.cc	l .	
·.		427/96,98,443.1.ccls.) and semiconductor) and	DERWENT	
		electroless ) and ((copper adj (sulfate or sulphate)) or	L.	